

■ Features

- SMD construction, and low profile.
- High Impedance and Excellent Frequency Characteristic.
- Self Electromagnetic Shielding.
- Low Magnetic Flux Leakage.

■ Applications

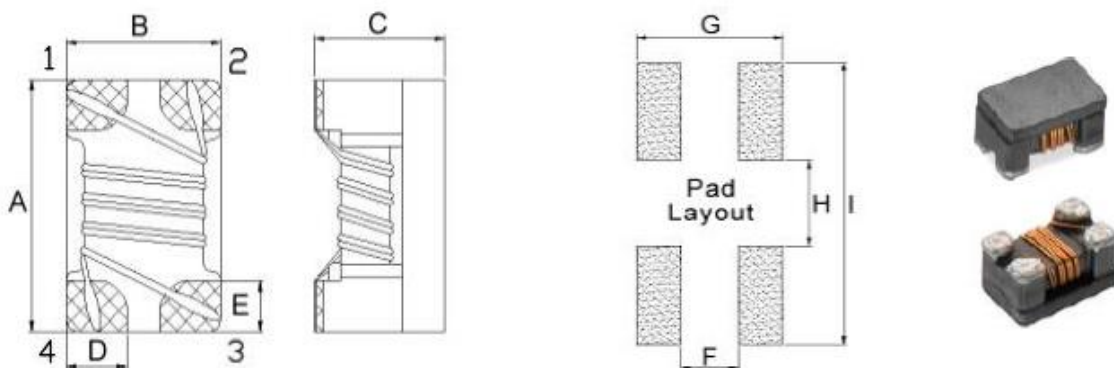
- LED Light, TV game, Monitor, etc.
- EMI common-mode noise.

■ Product Identification

YLCM □□□□□□ - □□□ T
 (1) (2) (3) (4)

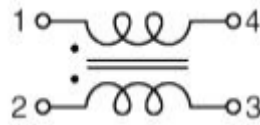
- (1) : Type
- (2) : Dimensions
- (3) : Impedance
- (4) : Taping

■ Shapes and Dimensions (Unit: mm)



TYPE	A	B	C	D Typ.	E Typ.	F Typ.	G Typ.	H Typ.	I Typ.
YLCM3225SP	3.2±0.2	2.5±0.2	2.2±0.2	0.9	0.8	0.6	3.5	1.6	4.4

■ Circuit Diagram



■ Note

- 1, No printing on the product.
- 2, Damage area diameter less than 0.3mm is allowed.

■ Electrical Characteristics

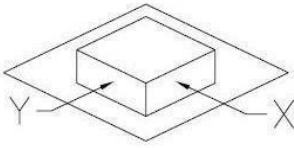
Part Number	Common mode Impedance (Ω @100MHz)	DC Resistance (m Ω)Max.	Rated Current (A)Max.	Rated Volt.(Vdc) Max.	IR(Ω)Min.
YLCM3225SP-102T-S1	1000 \pm 25%	100	1.5	50	10M

- 1. Rated Current: Temp.rise 40 $^{\circ}$ C Typ
- 2. Operating Temperature: -40 $^{\circ}$ C up to +125 $^{\circ}$ C
- 3.Storage Temperature: -20 $^{\circ}$ C up to +40 $^{\circ}$ C, 75% RH max.

■ Material List

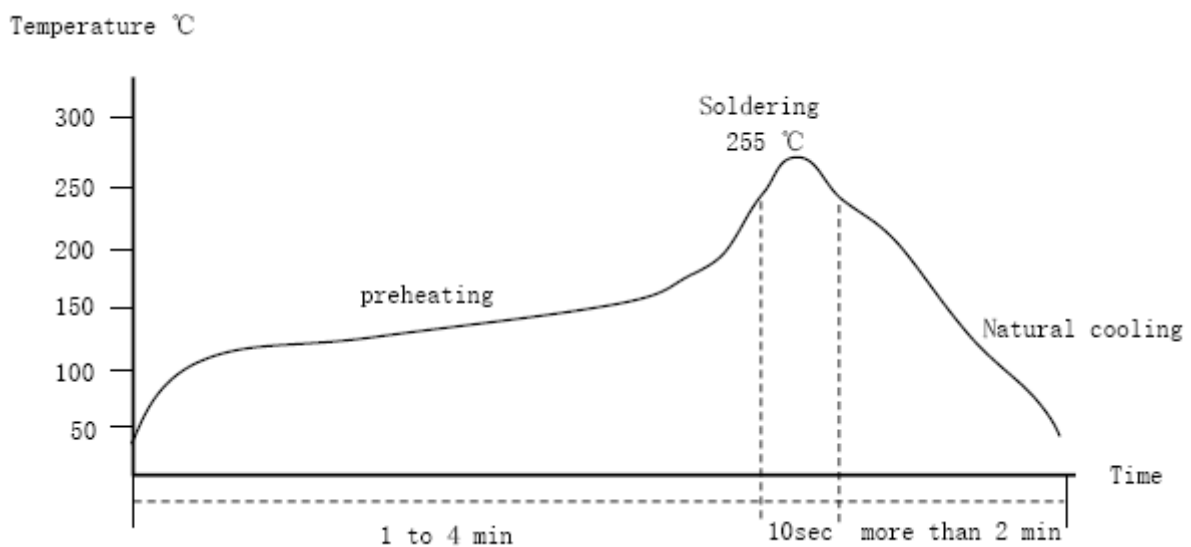
NO.	ITEM	DESCRIPTION
1	CORE	FERRITE
2	WIRE	P180 G1
3	ADHESIVE	5890LC
4	TIN	107H

Reliability Testing

Operating Temperature	- 40 to + 125 °C (Contain Heating coil)
Appearance Inspection	No external defects by visual inspection
Terminal Strength 	After soldering , between copper plaet and terminals of coils , push in two directions of X , Y with standing 10N(1.02kg) for10+/-2 sec. Terminal should not peel off. (Refer to figure at right)
Heat endurance of reflow soldering	Refer to figure
Insulating resistance	Over 100 MΩ at 100V D.C . between wire and core .
Dielectric Strength	Apply at 0.5KV 3mA for 1 minute between wire and core .
Temperature characteristics	Inductance coefficient (0~2,000) × 10 / °C (- 40 ~ + 125 °C)
Humidity characteristics	Inductance deviation within ± 10% , after 96 hours in 90~95% relative humidity at 40 ± 2 °C and 1 hours drying under normal condition .
A test is made under the above mentioned condition , and it is kept for 2 hours in the normal	

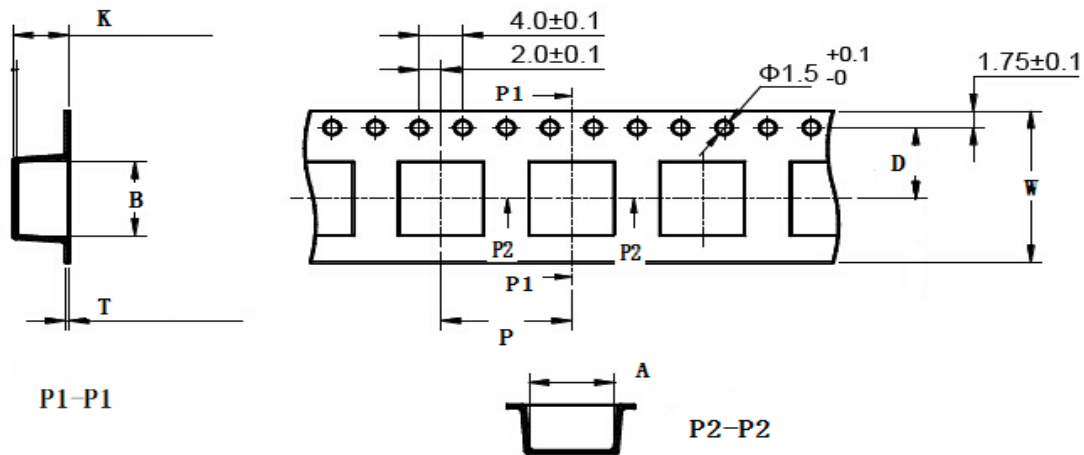
Recommended soldering temp.Graph

IR Reflow profile



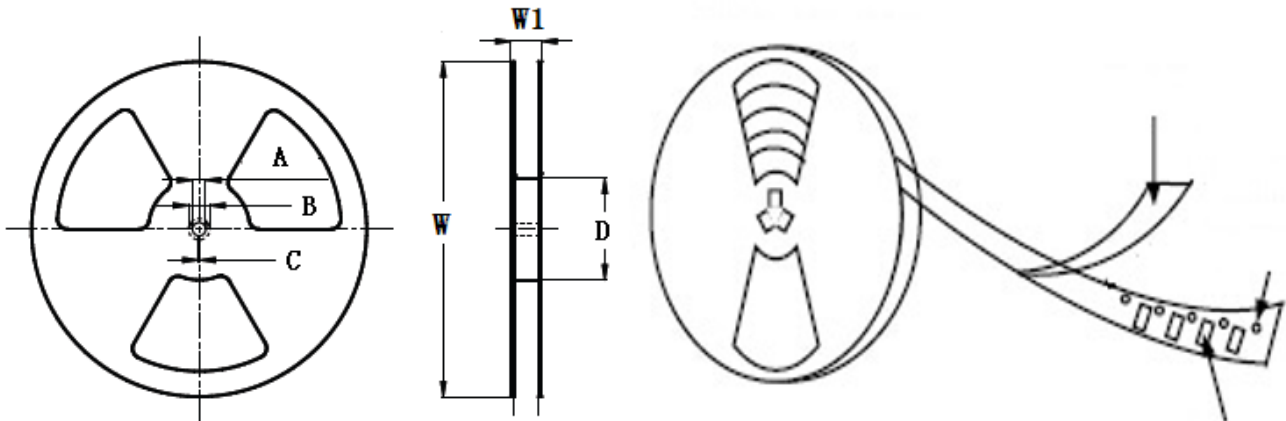
Temperature and humidity. After that,no mechanical and electrical defect should be found.

■ Taping Dimensions(Unit:mm)



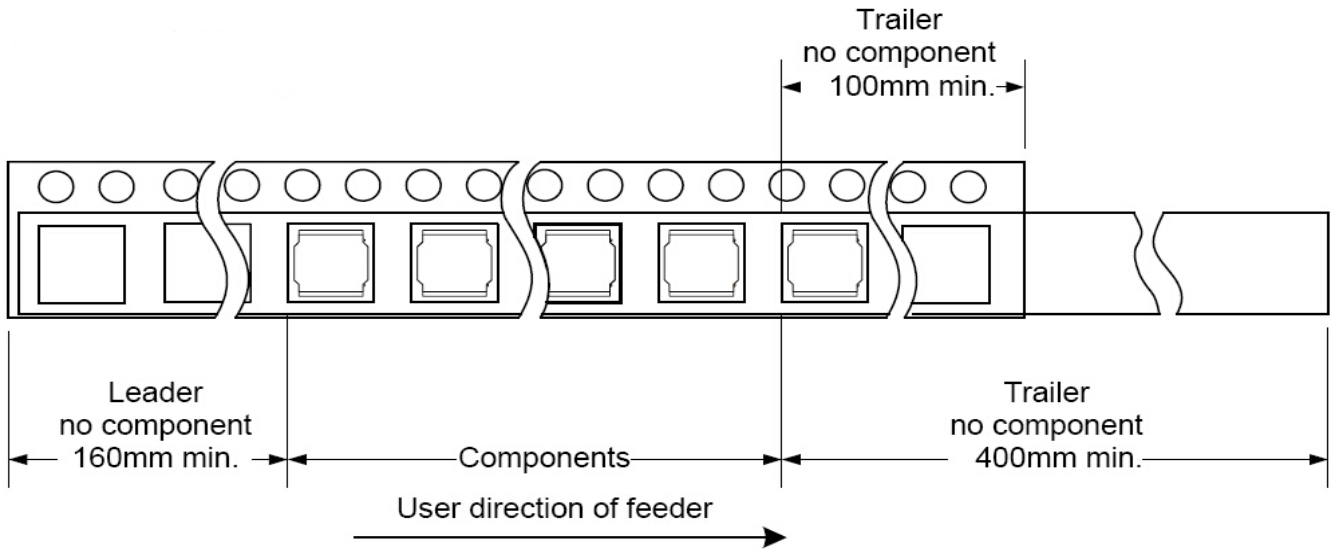
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YLCM3225SP	8.00	3.30	3.30	3.50	4.00	1.90	0.25	2000

■ Reel Dimensions(Unit:mm)

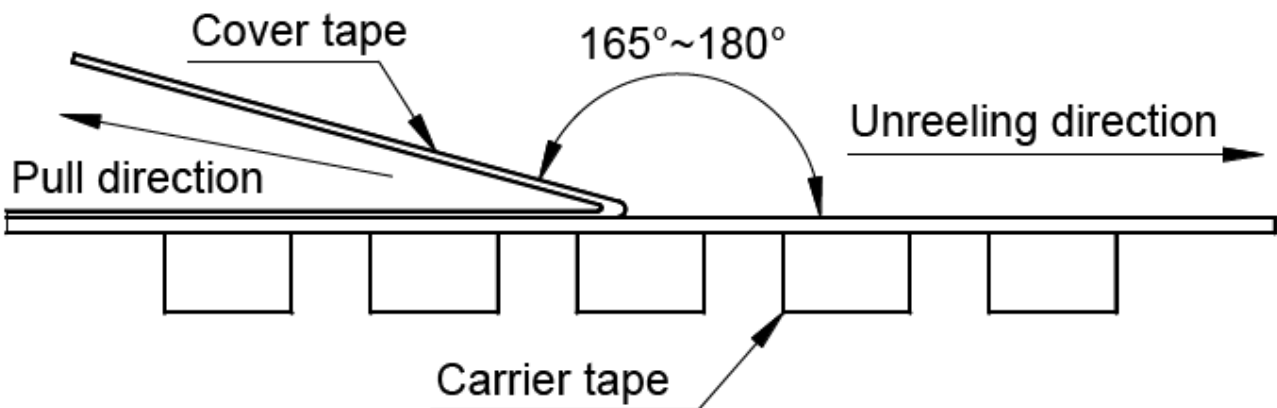


TYPE	W	W1	A	B	C	D
YLCM3225SP	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

■ Direction of rolling



Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.